

1st International Ceramic Interconnect and Ceramic Microsystems Technology Conference, April 10-13, 2005 Baltimore

Panel Discussion

Ceramic Microsystems: The Path Forward

Moderator: Dave Wilcox

Panel Members:

Mr. Dan Amey, E.I. DuPont

Mr. Jon Bost, JRB Consulting, LLC.

Mr. Arthur L.Chait, Eoplex Technologies, Inc.

Mr. Walter Roethlingshoefer, Robert Bosch GmbH

Prof. Andreas Roosen, U. of Erlangen-Nuremberg

Ceramic Microsystems Technologies: A Proposed Definition

Technologies that enable the integration and miniaturization of electronic, fluidic, photonic, thermonic and mechatronic devices using advanced ceramic processing to create new system level products or replace systems or sub-systems level products that are assembled from discrete components.

Panel Discussion Format

- Brief Introductions by panel members, position and background and interest in Ceramic Microsystems.
- What/where are the emerging market opportunities and what are or how does one determine these requirements?
- User facilities for MEMS prototyping exist at Universities and National Labs...would similar CICMT facilities be useful? How?
- What might the IMAPS/ACerS CICMT Org. Team, CICMT Advisory Board and ACerS/IMAPS Organizations do to accelerate the market impact of Ceramic Microsystems?
- Questions and comments from the floor.